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Pixus Develops OpenVPX Chassis Platform Supporting Speeds in Excess of 100GbE and 2500W of Cooling

Waterloo, Ontario — Jan 5, 2020 – Pixus Technologies, a provider of embedded computing and enclosure solutions, has provided the fastest known customized OpenVPX backplane/ chassis design in the market.

The 9U RiCool chassis platform for 6U OpenVPX boards features dual hot-swappable 191 CFM fans for cooling up to 2500W. The design allows the use of Rear Transition Modules (RTMs) in all slots. Rear-pluggable PSU's provide power for the VPX and custom rails, available in various wattage and output options.

The backplane design required routing for 28G+ signals across the backplane. This is in excess of the 4 x 25G speeds of 100GbE and the capability of the high-performance RT3 VPX connector. As such, a special high-speed connector was utilized for the 28G+ signals. The backplane also required VITA 66.5 and VITA 67.x interfaces for optical and RF through the printed circuit board.

Pixus offers high-performance OpenVPX and other open standard architecture backplanes, chassis platforms, and specialty products. The company also provides customizable faceplates, ejector handles, card guides, and other components.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.